



Material Content Data Sheet



Sales Product Name		BCR 08PN H6327		Issued		2. August 2018		
MA#		MA000846160						
Package		PG-SOT363-6-1		Weight*		6.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		16	
	noble metal	gold	7440-57-5	0.010	0.16		1595	
	inorganic material	silicon	7440-21-3	0.086	1.36	1.52	13623	15234
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		459	
	non noble metal	chromium	7440-47-3	0.009	0.14		1376	
	non noble metal	copper	7440-50-8	2.869	45.67	45.87	456636	458563
wire	non noble metal	copper	7440-50-8	0.010	0.16	0.16	1628	1628
encapsulation	organic material	carbon black	1333-86-4	0.030	0.48		4817	
	plastics	epoxy resin	-	0.651	10.36		103564	
	inorganic material	silicondioxide	60676-86-0	2.346	37.33	48.17	373312	481693
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33936	33936
plating	noble metal	silver	7440-22-4	0.056	0.89	0.89	8946	8946
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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